

INTRODUCE:

HVGT high voltage axial lead rectifier assembly is made of high quality silicon wafer chip and high reliability epoxy resin sealing structure, and through professional testing equipment inspection qualified after to customers.

FEATURES:

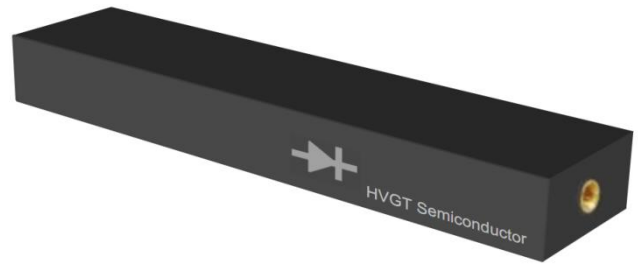
1. High reliability design.
2. Very high voltage.
3. High frequency, Fast recovery.
4. Conform to RoHS and SGS.
5. Epoxy resin molded in vacuum Have anticorrosion in the surface.

APPLICATIONS:

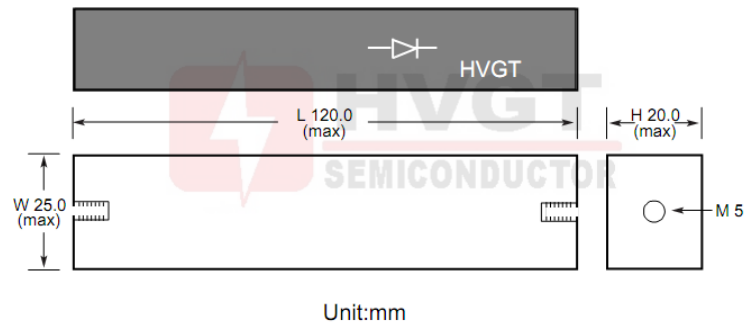
1. High voltage multiplier circuit
2. electrostatic precipitators.
3. General purpose high voltage rectifier.
4. Pulse rectifier circuit

MECHANICAL DATA:

1. Case: epoxy resin molding.
2. Terminal: screw holes.
3. Net weight: 90.0 grams (approx).

SHAPE DISPLAY:

SIZE: (Unit:mm)
HVGT NAME: HVC-122520
HVC-122520 Series

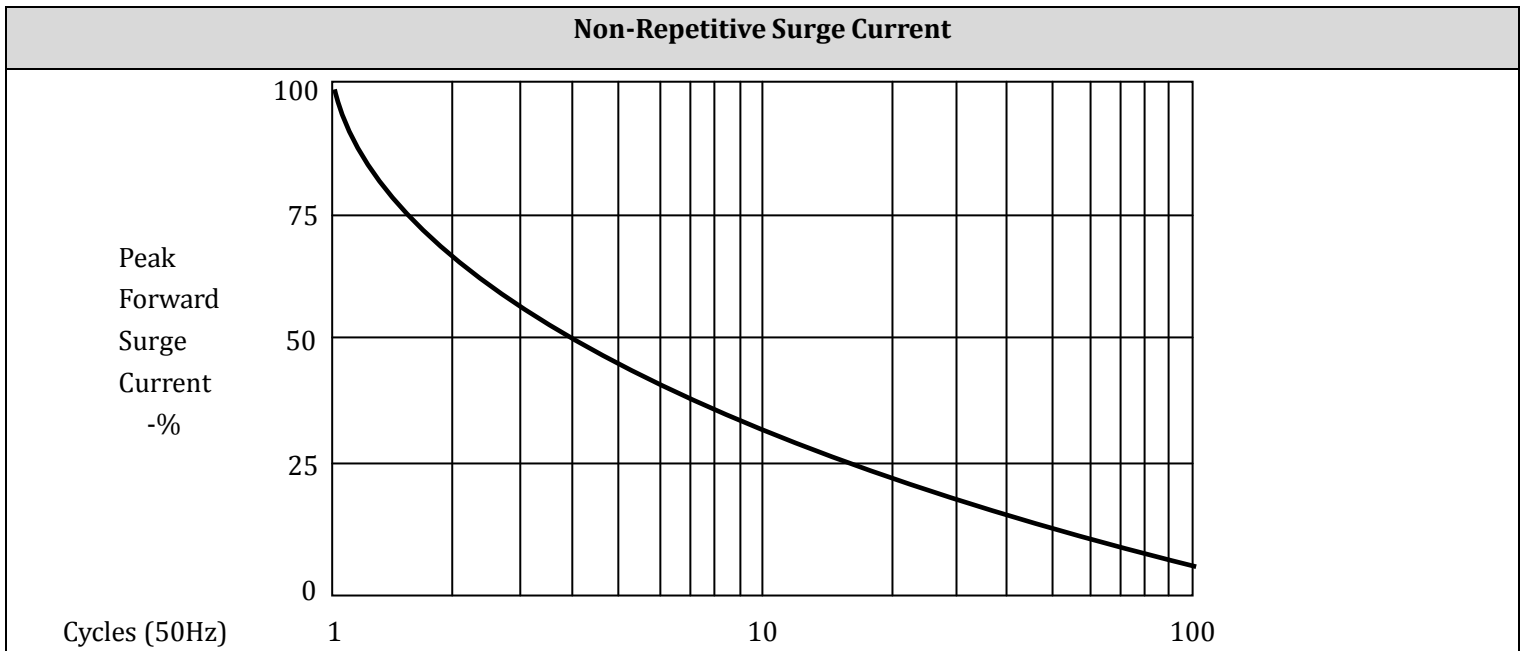
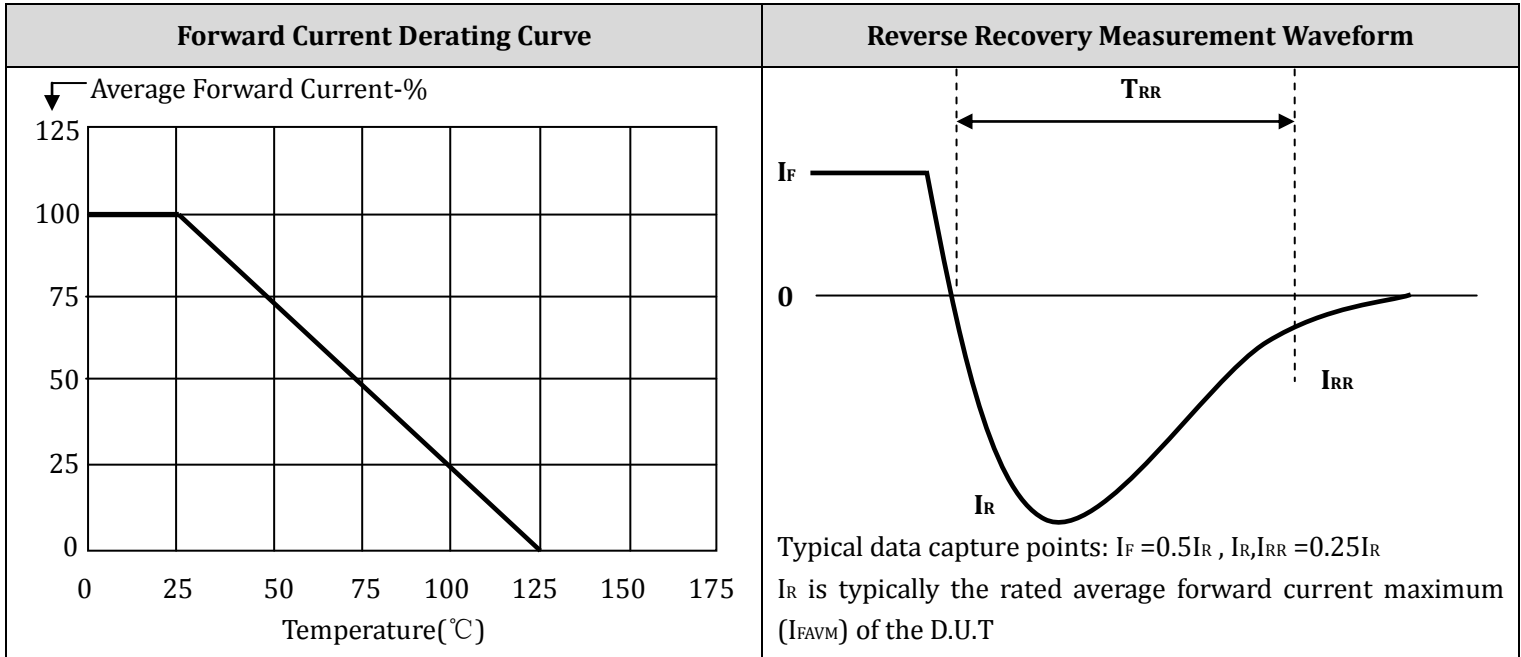
Screw Holes M5


MAXIMUM RATINGS AND CHARACTERISTICS: (Absolute Maximum Ratings)

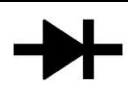
Items	Symbols	Condition	Data Value	Units
Repetitive Peak Reverse Voltage	V_{RRM}	$T_A=25^{\circ}C$	30	kV
Non-Repetitive Peak Reverse Voltage	V_{RSM}	$T_A=25^{\circ}C$	36	kV
Average Forward Current Maximum	I_{FAVM}	$T_A=25^{\circ}C$	0.5	A
		$T_{OIL}=55^{\circ}C$	0.5	A
Non-Repetitive Forward Surge Current	I_{FSM}	$T_A=25^{\circ}C$; 50Hz Half-Sine Wave; 8.3ms	15	A
Junction Temperature	T_J		125	$^{\circ}C$
Allowable Operation Case Temperature	T_C		-40~+125	$^{\circ}C$
Storage Temperature	T_{STG}		-40~+150	$^{\circ}C$

ELECTRICAL CHARACTERISTICS: $T_A=25^{\circ}C$ (Unless Otherwise Specified)

Items	Symbols	Condition	Data value	Units
Maximum Forward Voltage Drop	V_{FM}	at $25^{\circ}C$; at I_{FAVM}	43.2	V
Maximum Reverse Current	I_{R1}	at $25^{\circ}C$; at V_{RRM}	5.0	μA
	I_{R2}	at $100^{\circ}C$; at V_{RRM}	50	μA
Maximum Reverse Recovery Time	T_{RR}	at $25^{\circ}C$; $I_F=0.5I_R$; $I_R=I_{FAVM}$; $I_{RR}=0.25I_R$	75	nS
Junction Capacitance	C_J	at $25^{\circ}C$; $V_R=0V$; $f=1MHz$	--	pF



MARKING:

Type	Code	Cathode Mark
AW005S300U	AW005S300U HVGT	

PART NUMBER NOTE:

Type	Chip	$I_{F(AV)}$	Connecting end	V_{RRM}	T_{RR}
A	W	005	S	300	U
Assembly Series	Wafer Chip	0.5A	L=Lead S=Screw Holes	30kV	(U)75ns (G)100ns (D) Standard Recovery Time